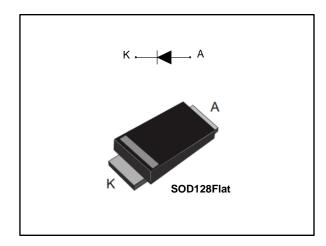


## STPS5H100AFY

## Automotive high voltage power Schottky rectifier

Datasheet - production data



#### **Description**

This high voltage Schottky barrier rectifier device is packaged in SOD128Flat and designed for high frequency miniature switched mode power supplies and for board DC to DC converters for automotive applications.

**Table 1: Device summary** 

Symbol	Value		
I <sub>F(AV)</sub>	5 A		
V <sub>RRM</sub>	100 V		
T <sub>j</sub> (max.)	175 °C		
V <sub>F</sub> (typ.)	0.51 V		

#### **Features**

- Negligible switching losses
- High junction temperature capability
- Low leakage current
- Good trade-off between leakage current and forward voltage drop
- Avalanche specification
- ECOPACK® compliant component
- AEC-Q101
- PPAP capable
- V<sub>RRM</sub> guaranteed from -40 to +175 °C

Characteristics STPS5H100AFY

### 1 Characteristics

Table 2: Absolute ratings (limiting values at 25 °C, unless otherwise specified)

Symbol	Pa	Value	Unit		
V <sub>RRM</sub>	Repetitive peak reverse voltage	e (T <sub>j</sub> = -40 °C to +175 °C)	100	V	
I <sub>F(AV)</sub>	Average forward current $T_L = 115 ^{\circ}\text{C}$ , $\delta = 0.5$ , square pulse		5	Α	
1	Surge non repetitive forward	ve forward $t_p = 10 \text{ ms sinusoidal}$		۸	
IFSM	I <sub>FSM</sub> current	t <sub>p</sub> = 8.3 ms sinusoidal	130	Α	
P <sub>ARM</sub>	Repetitive peak avalanche power $t_p = 10 \ \mu s, T_j = 125 \ ^{\circ}C$		300	W	
T <sub>stg</sub>	Storage temperature range		-65 to +175	°C	
Tj	Operating junction temperature	-40 to +175	°C		

#### Notes:

**Table 3: Thermal parameters** 

Syr	mbol	Parameter	Max. value	Unit
Rt	th(j-l)	Junction to lead	16	°C/W

**Table 4: Static electrical characteristics** 

Symbol	Parameter	Test conditions		Min.	Тур.	Max.	Unit
	Reverse leakage current	T <sub>j</sub> = 25 °C	V <sub>R</sub> = 100 V	-	0.7	3.5	μΑ
I <sub>R</sub> <sup>(1)</sup>		T <sub>j</sub> = 125 °C		-	1	4	mA
		T <sub>j</sub> = 150 °C		-		16	
	Forward voltage drop	T <sub>j</sub> = 25 °C	I <sub>F</sub> = 2.5 A	-		0.67	- V
V <sub>F</sub> <sup>(2)</sup>		T <sub>j</sub> = 125 °C		-	0.51	0.55	
VFI		T <sub>j</sub> = 25 °C	I <sub>F</sub> = 5 A	-		0.76	
		T <sub>j</sub> = 125 °C		-	0.57	0.61	

#### Notes:

 $^{(1)}$ Pulse test:  $t_p$  = 5 ms,  $\delta$  < 2%

 $^{(2)}$ Pulse test: t<sub>p</sub> = 380 µs,  $\delta$  < 2%

To evaluate the conduction losses use the following equation:

 $P = 0.49 \text{ x } I_{F(AV)} + 0.024 \text{ x } I_{F^2(RMS)}$ 

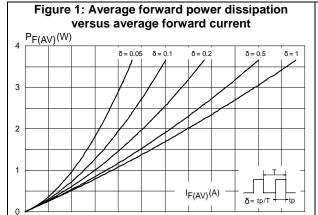
 $<sup>^{(1)}(</sup>dP_{tot}/dT_j) < (1/R_{th(j-a)}) \ condition \ to \ avoid \ thermal \ runaway \ for \ a \ diode \ on \ its \ own \ heatsink.$ 

STPS5H100AFY Characteristics

### 1.1 Characteristics (curves)

2

0



3

4

100

5

1000

Figure 2: Average forward current versus ambient temperature ( $\delta$  = 0.5)

12

IF(AV)(A)

10

8

6

4

2

0

0

25

50

75

100

125

150

175

Figure 3: Normalized avalanche power derating versus pulse duration

PARM(tp)
PARM(10 µs)

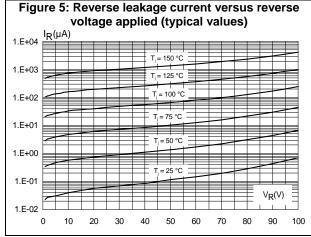
0.01

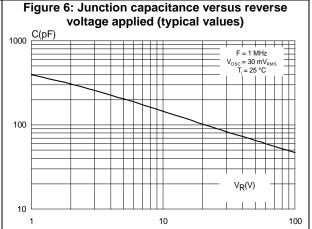
0.01

t,(µs)

10

Figure 4: Relative variation of thermal impedance junction to lead versus pulse duration  $Z_{th(j-l)}/R_{th(j-l)}$ 1.0 0.9 0.8 0.7 0.6 0.5 0.4 0.3 0.2 Single pulse 0.1 0.0 1.E-04 1.E-03 1.E-01 1.E+01





Characteristics STPS5H100AFY

current (typical values) 100.00 10.00 1.00 0.10  $V_{\mathsf{F}}(V)$ 0.01 0.0 0.1 0.2 0.3 0.4 0.5 0.6 0.7 8.0 0.9 1.0

Figure 7: Forward voltage drop versus forward

Figure 8: Thermal resistance junction to ambient versus copper surface under each lead (typical values, epoxy printed board FR4, e<sub>Cu</sub> = 35 µm)

Rth(j-a)(°C/W)

150

50

Soutcm²)

2.5

3.0

3.5

4.0 4.5 5.0

0.5

1.0

1.5 2.0

0.0

DocID029453 Rev 2

4/8

STPS5H100AFY Package information

### 2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: **www.st.com**. ECOPACK® is an ST trademark.

- Epoxy meets UL94, V0
- Lead-free package

### 2.1 SOD128Flat package information

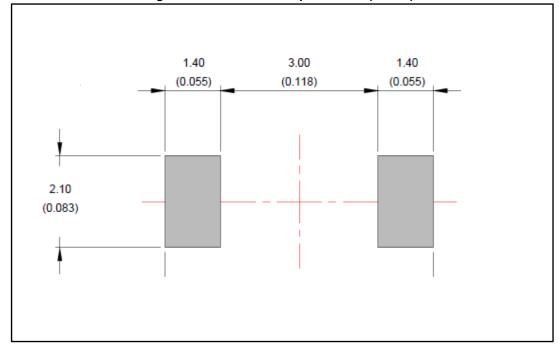
Figure 9: SOD128Flat package outline

577

Table 5: SOD128Flat package mechanical data

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	Dimensions			
Ref.	Millimeters		Inc	hes
	Min.	Max.	Min.	Max.
А	0.93	1.03	0.037	0.041
b	1.69	1.81	0.067	0.071
С	0.10	0.22	0.004	0.009
D	2.30	2.50	0.091	0.098
Е	4.60	4.80	0.181	0.189
E1	3.70	3.90	0.146	0.154
L	0.55	0.85	0.026	0.033
L1	0.30 typ.		0.012	2 typ.
L2	0.45 typ.		0.018	3 typ.

Figure 10: SOD128Flat footprint in mm (inches)



# 3 Ordering information

**Table 6: Ordering information** 

Order code	Marking	Package	Weight	Base qty.	Delivery mode
STPS5H100AFY	5H100Y	SOD128Flat	26.4 mg	3000	Tape and reel

# 4 Revision history

Table 7: Document revision history

Date	Revision	Changes
14-Jun-2016	1	Initial release.
24-Jun-2016	2	Updated Table 2: "Absolute ratings (limiting values at 25 °C, unless otherwise specified)".



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